

# Declaration of RoHS Compliance

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Company Name: E M Fluids Inc.  
Company Address: 1801 Woodward Dr.  
Ottawa, ON K2C 0R3  
Canada

Contact Person: Glenn Wagner, Engineering Manager  
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Product Name: EMF Device  
Model Number: EMF-AA01GLB-A  
Product Description: An innovative cleantech solution that leverages proprietary electromagnetic signals to influence and enhance waterbodies.

## Declaration

We hereby declare that the above-mentioned product, manufactured by E M Fluids, complies with the requirements of Directive 2011/65/EU (RoHS 2), as amended by Directive (EU) 2015/863, on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE).

This declaration is made to the best of our knowledge and under the sole responsibility of the manufacturer, based on supplier declarations, internal assessments, and reasonable due diligence.

This product is a complex article, composed of multiple constituent articles (components). The restricted substances listed below are not present in concentrations exceeding the maximum allowable limits in homogeneous materials, except where specific exemptions apply in accordance with Annex III of the RoHS Directive.

## Restricted Substances and Maximum Concentration Limits

Restricted Substance	Maximum Concentration Limit (by weight in homogeneous material)
Lead (Pb)	0.1%
Mercury (Hg)	0.1%
Cadmium (Cd)	0.01%
Hexavalent Chromium (Cr <sup>6+</sup> )	0.1%
Polybrominated Biphenyls (PBB)	0.1%
Polybrominated Diphenyl Ethers (PBDE)	0.1%
Bis(2-ethylhexyl) phthalate (DEHP)	0.1%
Butyl Benzyl Phthalate (BBP)	0.1%
Dibutyl Phthalate (DBP)	0.1%
Diisobutyl Phthalate (DIBP)	0.1%

## Applicable Exemptions

Certain constituent articles utilize the following valid exemptions from Annex III of the RoHS Directive:

- 6(b)-II: Lead as an alloying element in aluminium for machining purposes with a lead content up to 0.4% by weight — *used in spring retention component*
- 6(c): Copper alloy containing up to 4% lead by weight — *used in electronic connectors*
- 7(a)-I: Lead in high melting temperature type solders (i.e., lead-based alloys containing 85% or more lead by weight) — *used in internal interconnect of certain electronic components*
- 7(c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, or in a glass or ceramic matrix compound — *used in thick film resistors*

## Supporting Standards

This declaration is based on an internal compliance assessment carried out in accordance with:

- EN IEC 63000:2018 — Technical documentation for the assessment of electrical and electronic products with respect to the restriction of hazardous substances

Place: Ottawa, Canada

Date: [DD/MM/YYYY] 24/02/2026

Authorized Signature: 

Name: Colin Davis

Title: CTO